Nanoveu Limited
ACN 624 421 085
Level 45, 108 St Georges Terrace
Perth WA, 6000 Australia
+61 8 6244 9095
www.nanoveu.com

ASX RELEASE **25 March 2025**

ASX: NVU

Pitt Street Research Semiconductor Conference Presentation

Nanoveu Limited (ASX: NVU, OTCQB: NNVUF) ("Nanoveu" or the "Company"), a technology innovator across advanced semiconductor, visualisation, and materials science, is pleased to advise of its participation today at the Pitt Street Research Semiconductor Conference 2026.

Nanoveu's Director and EMASS founder, Dr Mohamed Sabry, will be presenting the Company's strategy for progressing its EMASS semiconductor business. Attached is the presentation that Dr Sabry will be speaking to at the conference.

This announcement has been authorised for release by the Board of Directors.

-ENDS-

Nanoveu Media
Alfred Chong, Nanoveu MD and CEO
P: +65 6557 0155
E: info@nanoveu.com

About Nanoveu Limited

Further details on the Company can be found at https://nanoveu.com/.

EMASS is a pioneering technology company specialising in the design and development of advanced systems-on-chip (SoC) solutions. These SoCs enable ultra-low-power, AI-driven processing for smart devices, IoT applications, and 3D content transformation. With its industry-leading technology, EMASS will enhance Nanoveu's portfolio, empowering a wide range of industries with efficient, scalable AI capabilities, further positioning Nanoveu as a key player in the rapidly growing 3D content, AI and edge computing markets.

EyeFly3D™ is a comprehensive platform solution for delivering glasses-free 3D experiences across a range of devices and industries. At its core, EyeFly3D™ combines advanced screen technology, sophisticated software for content processing, and now, with the integration of EMASS's ultra-low-power SoC, powerful hardware.

Nanoshield™ is a self-disinfecting film that uses a patented polymer of embedded Cuprous nanoparticles to provide antiviral and antimicrobial protection for a range of applications, from mobile covers to industrial surfaces. Applications include *Nanoshield™ Marine*, which prevents the growth of aquatic organisms on submerged surfaces like ship hulls, and *Nanoshield™ Solar*, designed to prevent surface debris on solar panels, thereby maintaining optimal power output.

Forward Looking Statements This announcement contains 'forward-looking information' that is based on the Company's expectations, estimates and projections as of the date on which the statements were made. This forward-looking information includes, among other things, statements with respect to the Company's business strategy, plans, development, objectives, performance, outlook, growth, cash flow, projections, targets and expectations and related expenses. Generally, this forward-looking information can be identified by the use of forward-looking terminology such as 'outlook', 'ambition', 'anticipate', 'project', 'target', 'potential', 'likely', 'believe', 'estimate', 'expect', 'intend', 'may', 'mission', 'would', 'could', 'should', 'scheduled', 'will', 'plan', 'forecast', 'evolve' and similar expressions. Persons reading this announcement are cautioned that such statements are only predictions, and that the Company's actual future results or performance may be materially different. Forward-looking information is subject to known and unknown risks, uncertainties and other factors that may cause the Company's actual results, level of activity, performance, or achievements to be materially different from those expressed or implied by such forward looking information.

About Nanoveu Limited

Further details on the Company can be found at https://nanoveu.com/.

EMASS is a pioneering technology company specialising in the design and development of advanced systems-on-chip (SoC) solutions. These SoCs enable ultra-low-power, AI-driven processing for smart devices, IoT applications, and 3D content transformation. With its industry-leading technology, EMASS will enhance Nanoveu's portfolio, empowering a wide range of industries with efficient, scalable AI capabilities, further positioning Nanoveu as a key player in the rapidly growing 3D content, AI and edge computing markets.

EyeFly3D™ is a comprehensive platform solution for delivering glasses-free 3D experiences across a range of devices and industries. At its core, EyeFly3D™ combines advanced screen technology, sophisticated software for content processing, and now, with the integration of EMASS's ultra-low-power SoC, powerful hardware.

Nanoshield™ is a self-disinfecting film that uses a patented polymer of embedded Cuprous nanoparticles to provide antiviral and antimicrobial protection for a range of applications, from mobile covers to industrial surfaces. Applications include *Nanoshield™ Marine*, which prevents the growth of aquatic organisms on submerged surfaces like ship hulls, and *Nanoshield™ Solar*, designed to prevent surface debris on solar panels, thereby maintaining optimal power output.

Forward Looking Statements This announcement contains 'forward-looking information' that is based on the Company's expectations, estimates and projections as of the date on which the statements were made. This forward-looking information includes, among other things, statements with respect to the Company's business strategy, plans, development, objectives, performance, outlook, growth, cash flow, projections, targets and expectations and related expenses. Generally, this forward-looking information can be identified by the use of forward-looking terminology such as 'outlook', 'ambition', 'anticipate', 'project', 'target', 'potential', 'likely', 'believe', 'estimate', 'expect', 'intend', 'may', 'mission', 'would', 'could', 'should', 'scheduled', 'will', 'plan', 'forecast', 'evolve' and similar expressions. Persons reading this announcement are cautioned that such statements are only predictions, and that the Company's actual future results or performance may be materially different. Forward-looking information is subject to known and unknown risks, uncertainties and other factors that may cause the Company's actual results, level of activity, performance, or achievements to be materially different from those expressed or implied by such forward looking information.

nanoveu

Pitt Street Research Semiconductor Conference 2026

PITT STREET RESEARCH

Disclaimer

IMPORTANT INFORMATION These presentation materials and any accompanying verbal presentation (together, the Presentation Materials) have been prepared by Nanoveu Limited (Company, NVU, Nanoveu) as at 23 March 2026 and statements are current only as at that date. Information in the Presentation Materials remains subject to change without notice. The Company has no responsibility or obligation to inform you of any matter arising or coming to its notice, after the date of this document, which may affect any matter referred to in this document. By receiving the Presentation Materials, you acknowledge and represent to the Company that you have read, understood and accepted the terms of this disclaimer. It is the responsibility of all recipients of these Presentation Materials to obtain all necessary approvals to receive these Presentation Materials and receipt of the Presentation Materials will be taken by the Company to constitute a representation and warranty that all relevant approvals have been obtained.

NOT AN OFFER These Presentation Materials are for information purposes only. The Presentation Materials do not comprise a prospectus, product disclosure statement or other offering document under Australian law (and will not be lodged with the Australian Securities and Investments Commission) or any other law. The Presentation Materials also do not constitute or form part of any invitation, offer for sale or subscription or any solicitation for any offer to buy or subscribe for any securities nor shall they or any part of them form the basis of or be relied upon in connection therewith or act as any inducement to enter into any contract or commitment with respect to securities. In particular, these Presentation Materials do not constitute an offer to sell or a solicitation to buy, securities in the United States of America.

NOT INVESTMENT ADVICE The Presentation Materials are not investment or financial product advice (nor tax, accounting or legal advice) and are not intended to be used for the basis of making an investment decision. Recipients should obtain their own advice before making any investment decision. This document does not constitute financial product advice or take into account your investment objectives, taxation situation, financial situation or needs. This document consists purely of factual information and does not involve or imply a recommendation of a statement of opinion in respect of whether to buy, sell or hold a financial product.

SUMMARY INFORMATION The information in this presentation has been prepared by the Company for the purposes of providing an overview of the Company and its products and technology. The Presentation Materials do not purport to be all inclusive or to contain all information about the Company or any of the assets, current or future, of the Company. The Presentation Materials contain summary information about the Company and its activities which is current as at the date of the Presentation Materials. The information in the Presentation Materials is of a general nature and does not purport to contain all the information which a prospective investor may require in evaluating a possible investment in the Company or that would be required in a prospectus or product disclosure statement or other offering document prepared in accordance with the requirements of Australian law or the laws of any other jurisdiction, including the United States of America.

NO LIABILITY The information contained in this document has been prepared in good faith by the Company however no guarantee, representation or warranty expressed or implied is or will be made by any person (including the Company and its affiliates and their directors, officers, employees, associates, advisers and agents) as to the accuracy, reliability, correctness, completeness or adequacy of any statements, estimates, options, conclusions or other information contained in this document. No person other than the Company is responsible for the preparation of this document. To the maximum extent permitted by law, the Company and its affiliates and their directors, officers, employees, associates, advisers and agents each expressly disclaims any and all liability, including, without limitation, any liability arising out of fault or negligence, for any loss arising from the use of or reliance on information contained in this document including representations or warranties or in relation to the accuracy or completeness of the information, statements, opinions, forecasts, reports or other matters, express or implied, contained in, arising out of or derived from, or for omissions from, this document including, without limitation, any financial information, any estimates, forecasts, or projections and any other financial information derived therefrom. Statements in this document are made only as of the date of this document unless otherwise stated and the information in this document remains subject to change without notice. No responsibility or liability is assumed by the Company or any of its affiliates (or their directors, officers, employees, associates, advisers and agents) for updating any information in this document or to inform any recipient of any new or more accurate in

FORWARD LOOKING STATEMENTS Statements contained in this document or made during or in connection with this presentation, including but not limited to those regarding the possible or assumed future production, costs, projected timeframes, performance, dividends, returns, revenue, exchange rates, potential growth of the Company , industry growth, product or price forecasts, or other projections and any estimated company earnings are or may contain or comprise forward looking statements. Forward looking statements can generally be identified by the use of words such as 'project', 'foresee', 'plan', 'expect', 'aim', 'anticipate', 'believe', 'estimate', 'may', 'should', or similar expressions. Forward looking statements including all statements in this presentation regarding the outcomes of studies, projections, guidance on future earnings and estimates are provided as a general guide only and should not be relied upon as an indication or guarantee of future performance. Although the Company believes that the expectations reflected in such forward looking statements are reasonable, these statements relate to future events and expectations and as such involve known and unknown risks and significant uncertainties, many of which are outside the control of the Company. Actual values, achievements, results, performance, actions and developments of the Company may differ materially from those projected, expressed or implied by the forward-looking statements in this document. Such forward looking statements speak only as of the date of this document. There can be no assurance that actual outcomes will not differ materially from these statements. To the maximum extent permitted by law, the Company and any of its affiliates and their directors, officers, employees, agents, associates and advisers disclaim any obligations or undertaking to release any updates or revisions to the information in this document to reflect any change in expectations or assumptions do not make any representation or warranty, express or implied, as to the accuracy, reliability or completeness of the information in this document, or likelihood of fulfilment of any forward looking statement or any event or results expressed or implied in any forward looking statement and disclaim all responsibility and liability for these forward looking statements (including without limitation, liability for negligence). Nothing in this document will under any circumstances create an implication that there has been no change in the affairs of the Company since the date of this document. Accordingly, you should not place undue reliance on any forward-looking statement.

ACCEPTANCE By attending a presentation or briefing, or accepting, accessing or reviewing this document you acknowledge, accept and agree to the matters set out above.

AUTHORISATION This document has been authorised for release by the Company's Board of Directors.

Capital Structure

Nanoveu Share Price

ASX - AUD

Nanoveu Limited (NVU.AX)

1D 5D 1M 6M YTD 1Y 5Y All

Capital Structure

ASX/OTCQB Code	NVU/NNVUF
Q4 2025 Cash	$1.8m
Cap Raise Jan 2026	$7.5m
Shares on Issue	1,080.4m
Options on Issue	269.9m
Average Volume	8.5m
Market Cap	$68.07m
Previous Close[1]	$0.063

1. As at close 23 March '26.

Board and Management

Dr. David Pevcic

Executive Chairman

- Experienced professional and investor in the resources and technology sector
- Non-Executive Chairman at Battery Age Minerals Ltd (ASX: BM8)
- Non-Executive Chairman at Infini Resources Ltd (ASX: I88)
- Holds a Bsc, MBBS, from the university of Western Australia

Dr. Mohamed Sabry

EMASS Founder and Director

- CTO, Founder of EMASS
- Associate Professor, NTU Singapore
- Postdoc at Stanford Univeristy
- Recipient of Nanyang Education Award
- Ph.D. from EPFL

Alfred Chong

Group CEO and Director

- Founder of Nanoveu, has 30+ years of experience in scaling companies and trade sales
- Former CEO of Atex Media Command (APAC), THISS Technologies, 121View
- Former CMO at 3D International

Steve Apedaile

Non-Executive Director

- 30 years of experience in accounting
- Worked at KPMG and Horwath Hong Kong
- Fellow of the ICAEW and Member of the AICD.
- Executive Chairman of Sprintex (ASX:SIX)

Raymond Chen

CFO and Director

- Held roles at Iluka Resources, NRW Holdings, Equinox Resources and KPMG
- MBA, University of Cambridge (Judge Business School)
- 15+ years' experience across resources and corporate finance

Semiconductor Leadership Team

Mark Goranson

CEO of Semiconductor Technology

- VP of Global Ops, TE Connectivity
- SVP of Fab Ops, ON Semi
- VP of Fab Ops, Freescale
- Early Member of Intel

Dr. Mohamed Sabry

CTO, Founder of EMASS

- Associate Professor, NTU Singapore
- Postdoc, Stanford
- Recipient of Nanyang Education Award
- Ph.D. from EPFL

Scott Smyser

VP, Sales & Marketing

- EVP Marketing & BD, Si-Ware Systems
- VP & GM, VTI Technologies (Murata)
- SVP Sales, Atomica
- SVP Strategic Sales, Rockley Photonics

EMASS Introduction

Fabless Semiconductor Innovator in Edge AI Processing

- Ultra-low-power Edge AI SoCs for always-on intelligence in battery constrained devices
- Flagship ECS-DoT chip up to 20x more energy efficient than peers
- Usable across drones, wearables, IoT devices and other Edge AI applications

Established Global Operations

- Global operations and R&D center's in USA, Singapore and Egypt
- 100% of EMASS acquired by Nanoveu Limited (ASX:NVU), March 2025

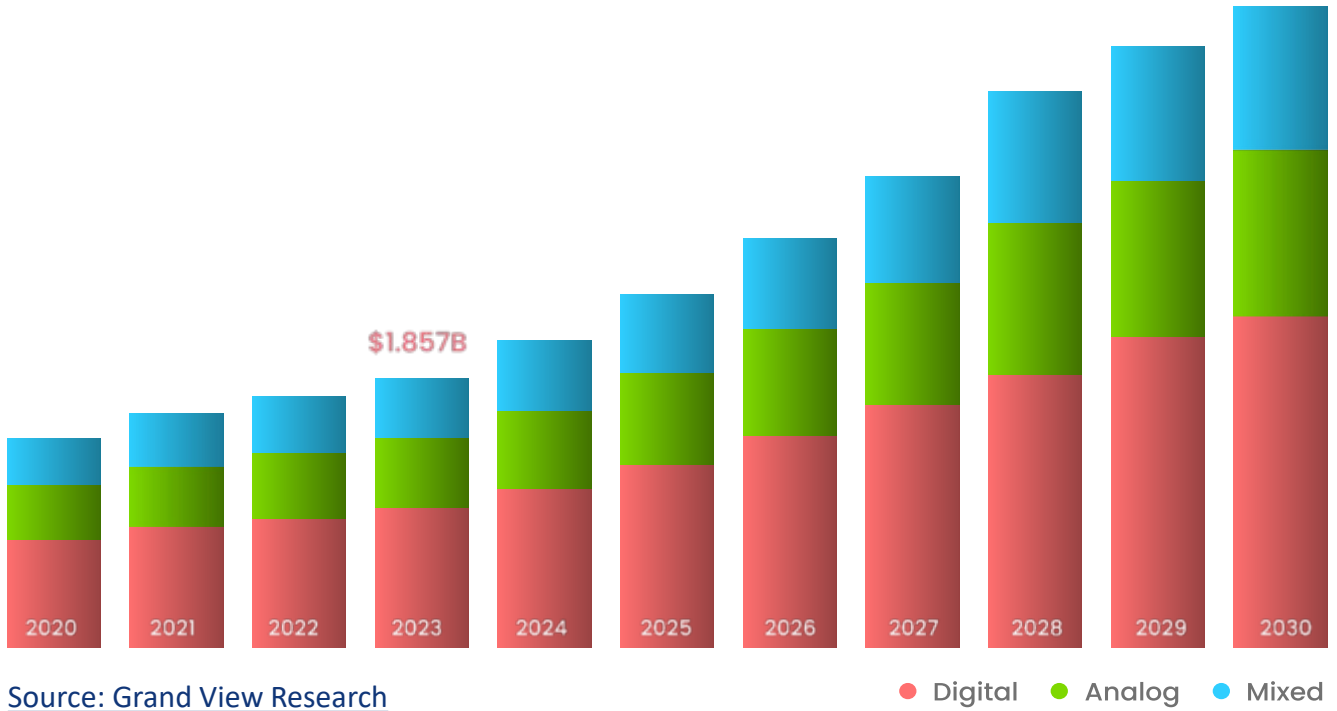
Expert Team Across Disciplines

- Deep expertise in AI/ML, neural network acceleration, semiconductor design, sensor fusion, and embedded systems
- Experienced management with semiconductor and AI industry backgrounds

Semiconductor & SoC Market Opportunity

System On Chip Market Size

By Type 2020-2030 (USD Billion)



Source: Grand View Research

SoC Market Growth:

Applications demanding continuous sensing, context awareness, and real-time decision-making

Set to hit

$325.7B by 2030

8.5% Global Market CAGR

Driven by AI, 5G, and smart devices.

Revolutionising Edge AI

Edge AI Opportunities

- Robust AI models require increased computation power and battery
- Current chips are not designed for efficient edge AI use cases
- Devices need versatile chips with multi-sensor use-cases

EMASS Solution

- Executes AI inference directly at the sensor under 1 mW power
- Provides up to 20x energy efficiency vs leading chips
- Enables smaller, lower-cost, and reconfigurable designs across drones, IoT, and wearables

Target Edge AI Sectors

Hearables

$USD 138.5B by 2029

Source: Marketsandmarkets

Wearables

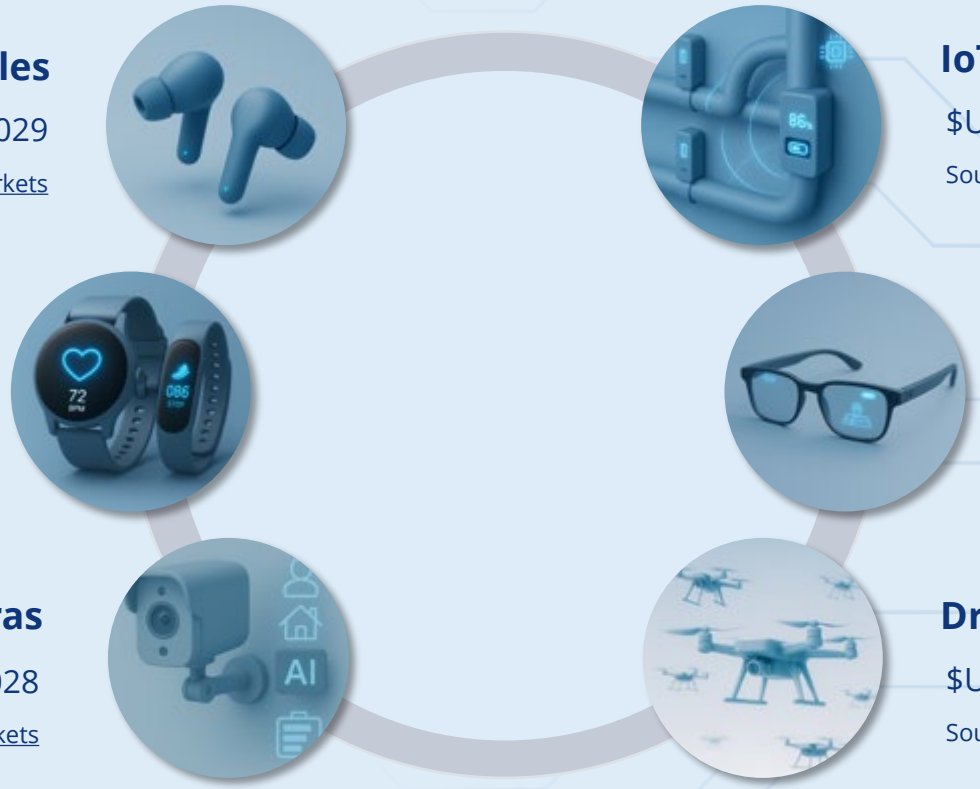
$USD 368.4B by 2035

Source: Fact.MR

AI Cameras

$USD 22.1B by 2028

Source: Marketsandmarkets



IoT Sensory

$USD 168.69B by 2030

Source: Mordor Intelligence

AR Glasses

$USD 8.26B by 2030

Source: Grand View Reasearch

Drones

$USD 223.66B by 2034

Source: Fact.MR

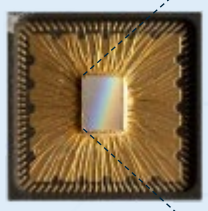
Redefining What's Possible
in Ultra-Low-Power Edge AI

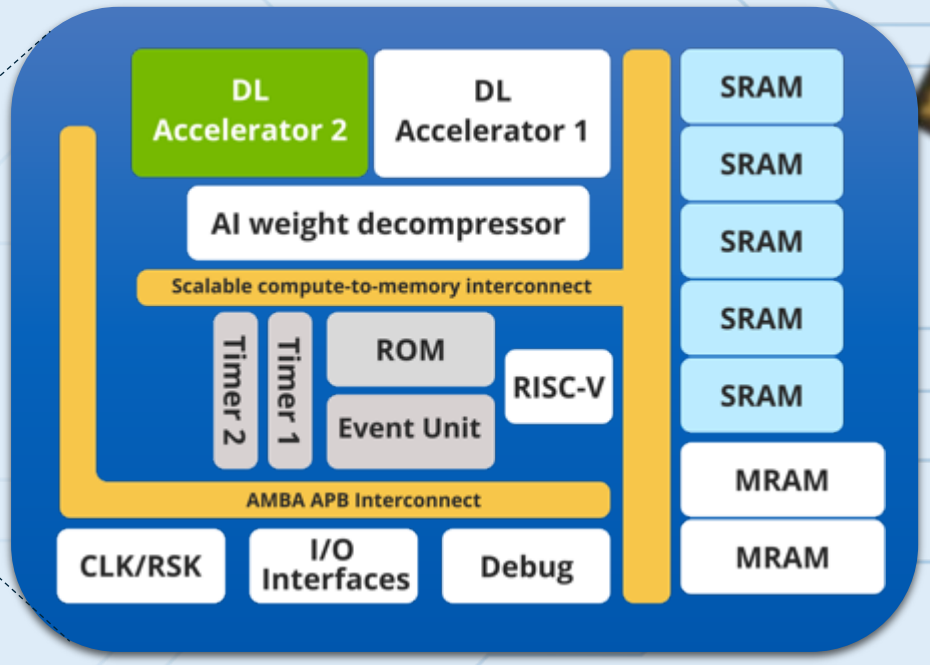
Fully Programmable System on Chip (SoC)

- Processor
- AI engines
- IPs for compressed AI

Local decision-making at the Edge

- Always-on AI Inference
- Sensor fusion
- Support CNNs, ML, Data Processing, etc.





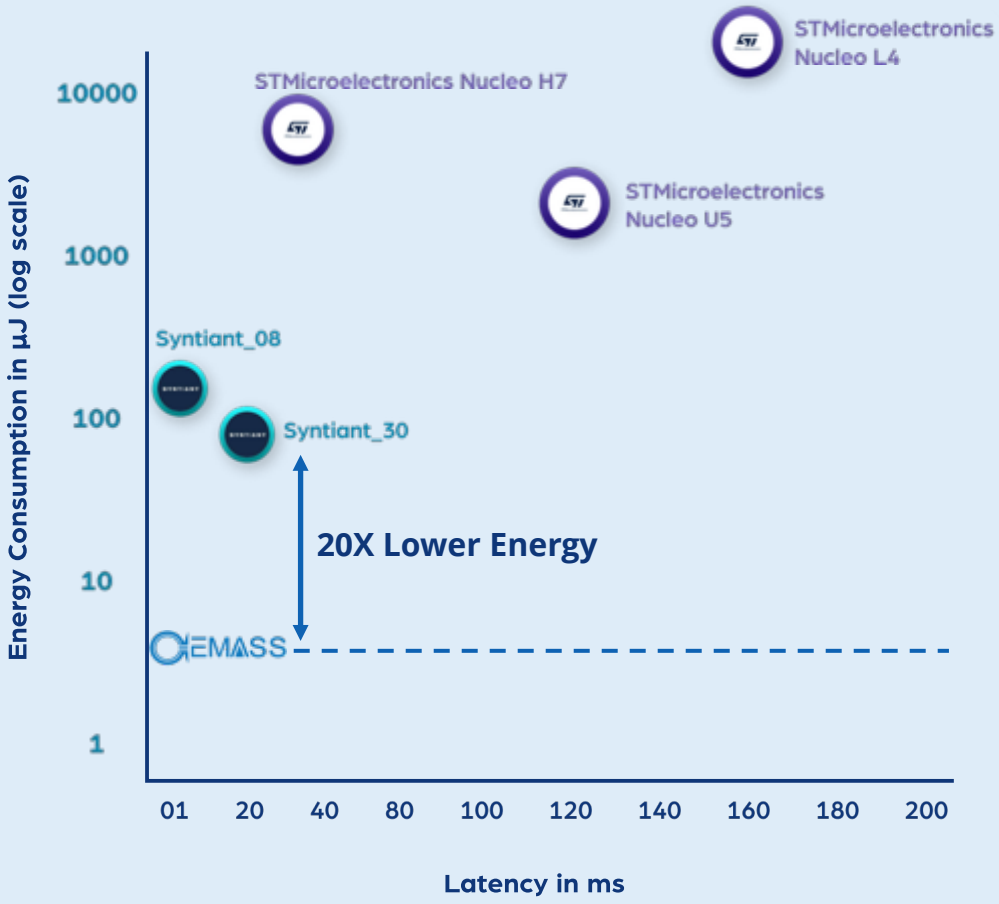
Key Architecture Features

- <1 to 5 mW power consumption (Avg 2mW always on)
- No External DRAM needed (very fast on-chip SRAM and nonvolatile MRAM/RRAM)
- SW and HW support for highly compressed AI workloads

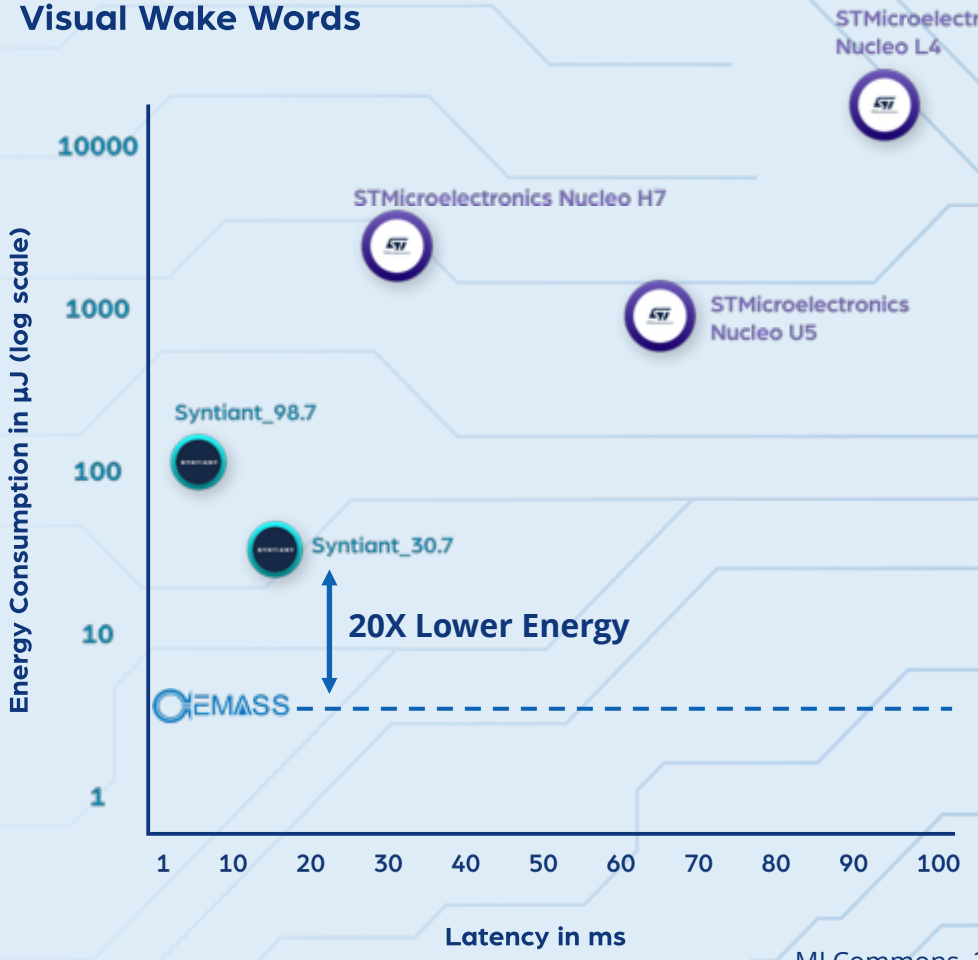
Exceptional AI Computation

20X Lower Energy

Image Classification



Visual Wake Words

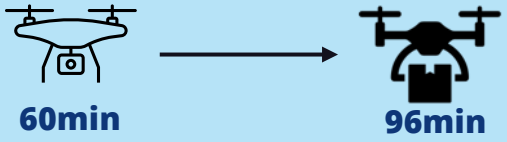


MLCommons, 2025

Breakthrough in Drone Endurance

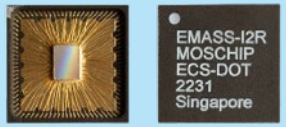
Longer Flight Times

+60% increase in flight time without any hardware changes



AI Ready Platform

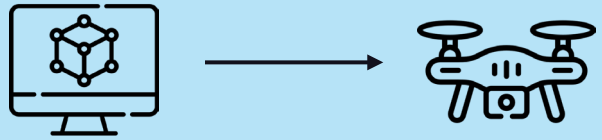
Enables onboard intelligence for mission-critical use cases



- Precision Landing
- Predictive Maintenance

Live Trials Underway

Bridging simulation to reality. Results expected in April 2026



How it works

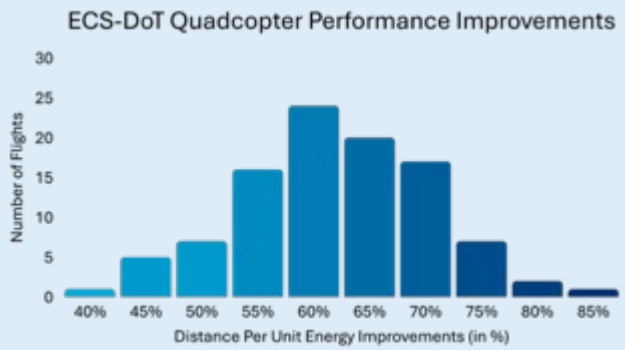
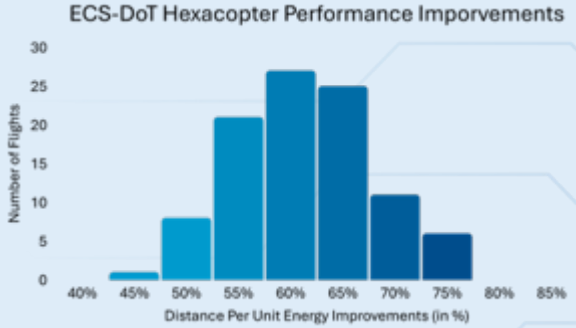
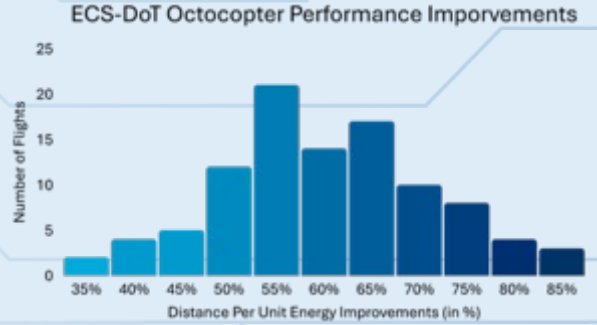
Real-time control @ 50hz executing full “sense-think-act” loop every 20ms

Operates in sub-milliwatt power envelope

AI engines include:

- Surrogate power predictor (25% drop in overthrust)
- Reinforcement learning controller (improves distance per Watt by 20%)

ECS-DoT Achieves Major Drone Performance Gains

Drone Type	Quadcopter	Hexacopter	Octocopter
Graph			
Use-cases	• Consumer • Enterprise	• Agriculture • Logistics • Terrain Mapping	• Industrial inspection • Defense • Professional
Performance Gains	Achieved up **to 80% improvement** in mission endurance, with a **60% average** extended flight time over baseline	Delivered up to **75% improvement** in flight endurance, with an average	Delivered consistent flight **endurance up to 85% with an average 57%** improvement

Live Drone Trials Update

Status update:

Live drone data log captured

AI model trained with live drone data

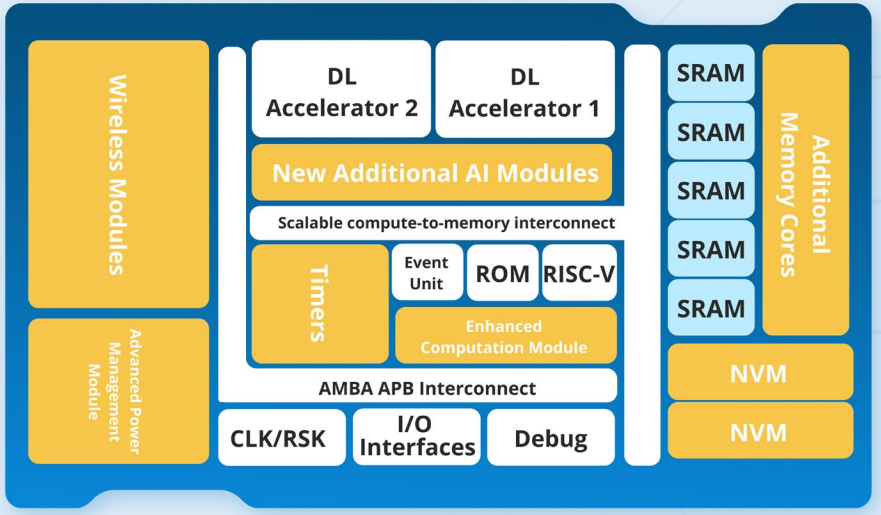
ECS-DoT Hardware integration with the drone

Performing Hardware-in-the-loop testing with custom simulator provided by partner

Expected live drone trials March end- April 2026

Next Generation ECS-DoT-16

Strengthening Leadership in Ultra-Low-Power Edge AI



Enhancement Highlights

- Fully integrated Low Energy Bluetooth (BLE)
- New Adaptive Power Management
- Dedicated AI module for object detection
- Expanded on-chip memory
- Integrated Floating-Point Unit (FPU)

Next Generation ECS-DoT 16nm

Enhancement Benefits

Dedicated AI Acceleration Module for Object Detection

- YOLO (You Only Look Once)-Nano-class architectures;
- MobileNet-SSD style detection heads; and
- FOMO (Faster Objects, More Objects)-style event and object detectors

New Adaptive Fine-Grained Power-Management Architecture

- Dynamic clock gating for workload-aware optimization
- Autonomous low-power states
- Microsecond-level sleep/wake

Integrated Floating-Point Unit (FPU)

- Accelerate DSP
- Enable mixed-precision AI workflows
- Improved developer experience

Integrated Bluetooth Low Energy Subsystem (Analog + RF)

- Eliminates external wireless ICs
- Reduces board area, BOM, and design complexity

Expanded On-chip Memory

- Support larger/complex neural networks
- Reduce off-chip memory

Award Winning SoC Performance

ECS-DoT won best in show for AI and Machine Learning

- At two of the largest shows in the industry – CES & embedded world
- Major accolades for innovative architecture and superior performance
- Ultra-low-power, RISC-V based SoC delivering real-time edge AI processing for vision, audio, and sensor data
- Showcased multiple demos with ECS-DoT including: predictive maintenance, audio security detection, wrist-worn wearable and bond-conduction audio

Strong Commercial Momentum

Customer & Partner Engagements

OEM engagements – eval boards shipped

- Wearables – AR glasses, hearables
- Dash cam
- Predictive maintenance

Partner collaborations – reference designs

- Inertial sensors
- Image sensors
- Spectral sensors

Select commercial partners/collaborators

What the Market is Responding To

Ultra-low power AI inference

- < 10 ms vs. 150-300 ms for competitors
- Up to 20X lower energy consumption vs. competitors

AI Model Portability

- Supports a wide range of AI Models
- Fast and easy development cycle
- Interoperability

Multi Sensor Integration

- Seamless integration with a variety of sensor types
- Real-time fusion of audio, motion and environmental data

Arrow Electronics Collaboration

Arrow Electronics (NYSE: ARW)

- Global technology distributor and engineering partner
- 2024 global sales of US$28 billion

Collaboration with EMASS

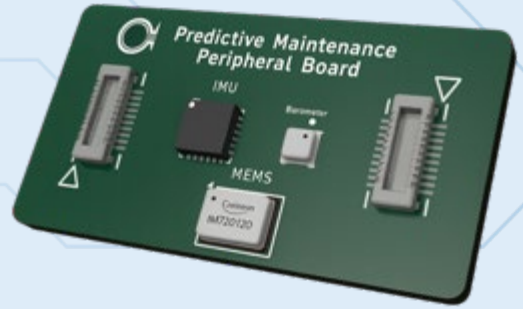
- Enhanced SDKs, developer tools, reference designs

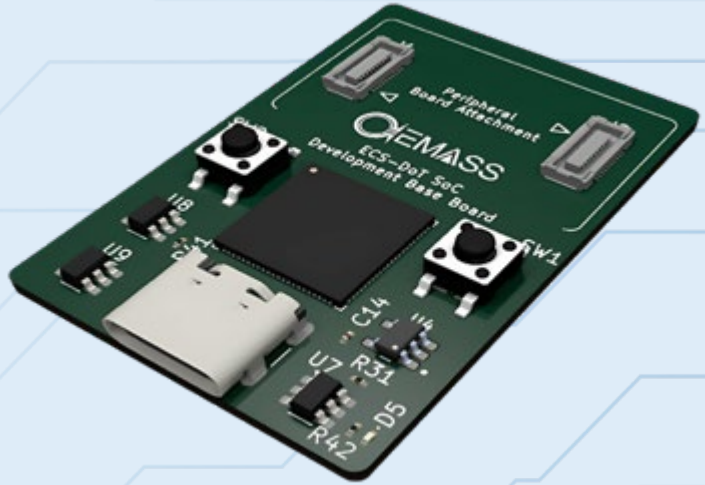
Predictive maintenance first reference design

- Cold asset tracking next design

Comarketing to customers

- Expand customer reach and engagement





Ref announcement 29 Oct 2025. Arrow Electronics Fact Sheet 6 Feb 25.

Semtech Collaboration

Semtech Corporation (Nasdaq: SMTC)

- Global semiconductor provider
- 2024 global sales of US$800 million plus

Collaboration with EMASS

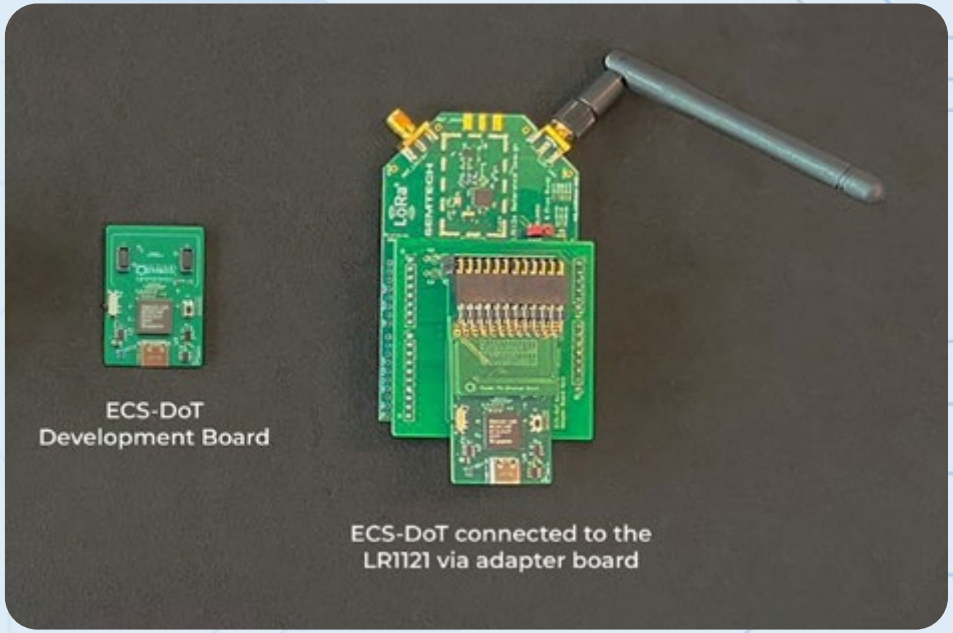
- Combine Semtech's LoRaWAN wireless transceiver with ECS-DoT (demo showcased at CES 2026)

Reference designs

- Predictive maintenance
- Security detection

Comarketing to customers

- Expand customer reach and engagement



Advancing Hearables

Reference design integrating STMicroelectronics inertial sensing with EMASS ECS-DoT

ECS-DoTs Highlights on the Reference Design

Sub-10ms

Local inference means voice commands are acted on in real time.

No Cloud

Keyword recognition runs entirely on-device, eliminating latency

Always-on

Motion-triggered wake-up ensures extended battery runtime significantly

Validated

The reference design gives product teams a fast-track path to integration

Key Reference Design Details

Design Part	Details
Processor	ECS-DoT edge-AI SoC (RISC-V based, sub-milliwatt operation)
Sensor	ST LSM6DSV16BX MEMS IMU — detects jaw movement to trigger wake-up
Function	Always-on keyword spotting via bone-conduction audio
Pipeline	Motion-triggered activation → on-device audio classification → keyword recognition

Scaling Commercial Operations

USA

Continued Customer Engagement

- Added sales director & field applications engineer
- Continued OEM engagement

EU

Setting up EU Operations

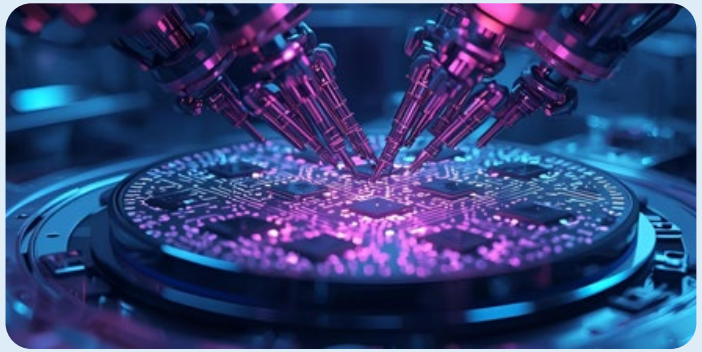
- Sales director
- New distribution partner

Asia

Application-Led Engagement

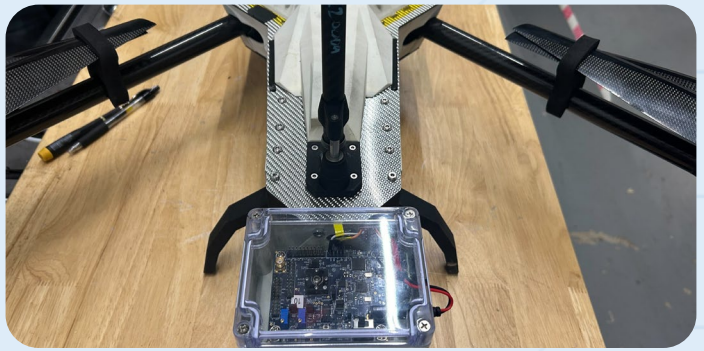
- Added sales rep
- New distribution partner

Upcoming Technical Catalysts



ECS-DoT 16nm and beyond

- Strengthening leadership in ultra-low-power Edge AI
- Integration of key chip enhancements
- Designed to further reduce power consumption while supporting larger and more complex AI models



Live-drone flight validation

- Validate performance gains from simulations
- Assess power consumption, latency, and endurance in live flight conditions

Drone Technology Expansion

- Building on recent drone technology licensing
- Developing integrated edge AI solutions for the broader drone ecosystem
- Positioning for high-growth drone markets

Upcoming Commercial Catalysts

Expanding Use-cases and Environments for ECS-DoT

- Improvements across evaluations and demos with ECS-DoT including:
  - Predictive maintenance
  - Security detection
  - Wrist-worn wearable
  - Cold asset tracking

More partner engagements

- Reference designs with ECS-DoT
- Comarketing
- Easier customer adoption

Targeting First Sales of ECS-DoT in 2026

- OEMs with eval boards
- Design-in process started
- More customer demand

nanoveu

Thank You

Head Office

Level 45, 108 St Georges Terrace

Perth WA, 6000 Australia

+61 8 6244 9095

www.nanoveu.com

Singapore Office

Symbiosis 3 Fusionopolis Way

13-21 Singapore 138633

+65 6557 0155